

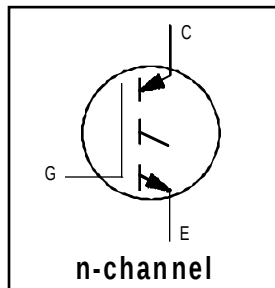
Features

- Electrically Isolated and Hermetically Sealed
- Simple Drive Requirements
- Latch-proof
- Fast Speed operation 3 kHz ~ 8 kHz
- High operating frequency
- Switching-loss rating includes all "tail" losses
- Ceramic eyelets

Description

Insulated Gate Bipolar Transistors (IGBTs) from International Rectifier have higher usable current densities than comparable bipolar transistors, while at the same time having simpler gate-drive requirements of the familiar power MOSFET. They provide substantial benefits to a host of high-voltage, high-current applications.

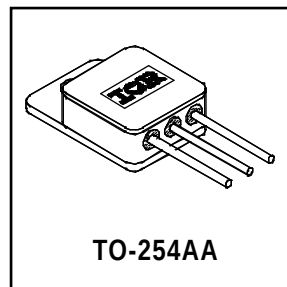
The performance of various IGBTs varies greatly with frequency. Note that IR now provides the designer with a speed benchmark ($f_{IC/2}$, or the "half-current frequency"), as well as an indication of the current handling capability of the device.



$$V_{CES} = 1200V$$

$$V_{CE(sat)} \leq 3.6V$$

$$@V_{GE} = 15V, I_C = 13A$$



TO-254AA

Absolute Maximum Ratings

	Parameter	Max.	Units
V_{CES}	Collector-to-Emitter Breakdown Voltage	1200	V
$I_C @ T_C = 100^\circ C$	Continuous Collector Current	13	A
I_{CM}	Pulsed Collector Current ①	48	
$I_C @ T_C = 25^\circ C$	Continuous Collector Current	24	
V_{GE}	Gate-to-Emitter Voltage	± 20	V
I_{LM}	Clamped Inductive Load Current ②	48	A
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	96	W
$P_D @ T_C = 100^\circ C$	Maximum Power Dissipation	38	
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to + 150	$^\circ C$
	Lead Temperature, for 10 seconds	300 (1.6mm from case)	
	Weight	9.3 (typical)	g

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	—	1.3	$^\circ C/W$
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	0.21	—	
$R_{\theta JA}$	Junction-to-Ambient, typical socket mount	—	48	

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)CES}$	Collector-to-Emitter Breakdown Voltage	1200	—	—	V	$V_{GE} = 0V, I_C = 250\mu A$
$V_{(BR)ECS}$	Emitter-to-Collector Breakdown Voltage ④	17	—	—	V	$V_{GE} = 0V, I_C = 1.0A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Temperature Coeff. of Breakdown Voltage	—	1.1	—	V/ $^\circ\text{C}$	$V_{GE} = 0V, I_C = 1.0mA$
$V_{CE(ON)}$	Collector-to-Emitter Saturation Voltage	—	2.4	3.6	V	$V_{GE} = 15V, I_C = 13A$ See Fig. 2, 5
		—	3.1	—		$V_{GE} = 15V, I_C = 24A$
		—	2.6	—		$V_{CE} = 15V, I_C = 13A, T_J = 125^\circ\text{C}$
$V_{GE(th)}$	Gate Threshold Voltage	3.0	—	5.5		$V_{CE} = V_{GE}, I_C = 250\mu A$
$\Delta V_{GE(th)}/\Delta T_J$	Temperature Coeff. of Threshold Voltage	—	-11	—	mV/ $^\circ\text{C}$	$V_{CE} = V_{GE}, I_C = 250\mu A$
g_{fe}	Forward Transconductance ⑤	5.0	—	—	S	$V_{CE} \geq 15V, I_C = 13A$
I_{CES}	Zero Gate Voltage Collector Current	—	—	100	μA	$V_{GE} = 0V, V_{CE} = 960V$
		—	—	1200		$V_{GE} = 0V, V_{CE} = 960V, T_J = 125^\circ\text{C}$
I_{GES}	Gate-to-Emitter Leakage Current	—	—	± 100	nA	$V_{GE} = \pm 20V$

Switching Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
Q_g	Total Gate Charge (turn-on)	—	56	84	nC	$I_C = 13A$
Q_{ge}	Gate - Emitter Charge (turn-on)	—	12	18		$V_{CC} = 400V$ See Fig. 7
Q_{gc}	Gate - Collector Charge (turn-on)	—	20	30		$V_{GE} = 15V$
$t_{d(on)}$	Turn-On Delay Time	—	25	—	ns	$T_J = 25^\circ\text{C}$ $I_C = 13A, V_{CC} = 960V$ $V_{GE} = 15V, R_G = 10\Omega$ Energy losses include "tail"
t_r	Rise Time	—	14	—		
$t_{d(off)}$	Turn-Off Delay Time	—	270	—		
t_f	Fall Time	—	270	—		
E_{on}	Turn-On Switching Loss	—	0.50	—	mJ	See Fig. 10, 11, 13, 14
E_{off}	Turn-Off Switching Loss	—	2.6	—		
E_{ts}	Total Switching Loss	—	3.1	4.7		
$t_{d(on)}$	Turn-On Delay Time	—	25	—	ns	$T_J = 125^\circ\text{C}$, $I_C = 13A, V_{CC} = 960V$ $V_{GE} = 15V, R_G = 10\Omega$ Energy losses include "tail"
t_r	Rise Time	—	14	—		
$t_{d(off)}$	Turn-Off Delay Time	—	450	—		
t_f	Fall Time	—	640	—		
E_{ts}	Total Switching Loss	—	7.5	—	mJ	See Fig. 13, 14
L_s	Internal Source Inductance	—	8.7	—	nH	Measured 5mm from package
C_{ies}	Input Capacitance	—	1400	—	pF	$V_{GE} = 0V$ $V_{CC} = 30V$ See Fig. 6 $f = 1.0MHz$
C_{oes}	Output Capacitance	—	82	—		
C_{res}	Reverse Transfer Capacitance	—	17	—		
C_{CC}	Case-to-Drain Capacitance	—	12	—		

Notes:

① Repetitive rating; $V_{GE} = 20V$, pulse width limited by max. junction temperature.
(See fig. 13b)

③ Repetitive rating; pulse width limited by maximum junction temperature.

⑤ Pulse width 5.0 μs , single shot.

② $V_{CC} = 80\%(V_{CES})$, $V_{GE} = 20V$, $L = 10\mu H$, $R_G = 10\Omega$, (See fig. 13a)

④ Pulse width $\leq 80\mu s$; duty factor $\leq 0.1\%$.

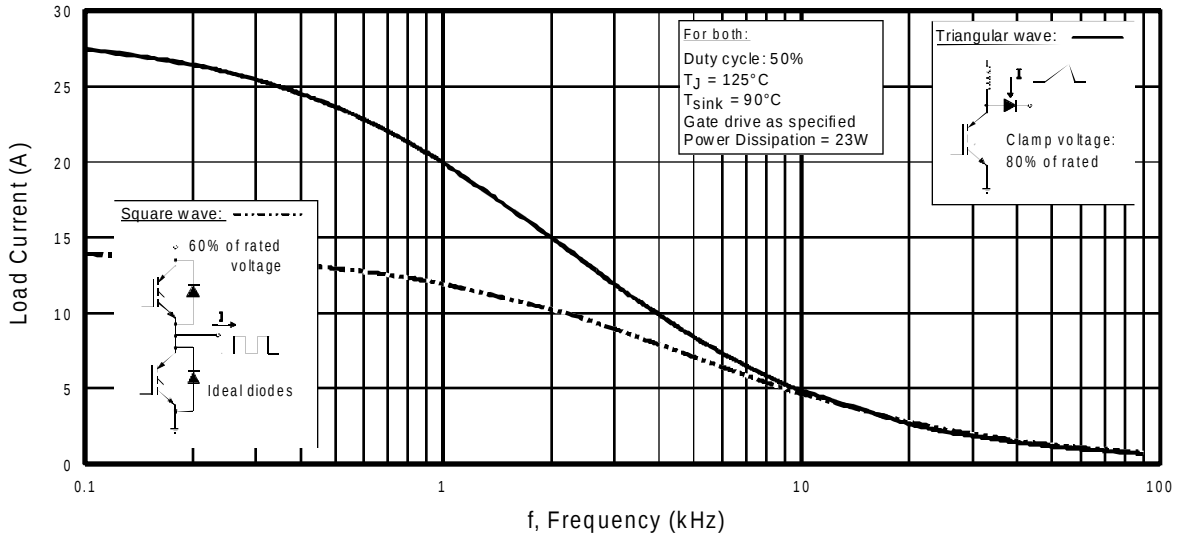


Fig. 1 - Typical Load Current vs. Frequency
(For square wave, $I = I_{\text{RMS}}$ of fundamental; for triangular wave, $I = I_{\text{PK}}$)

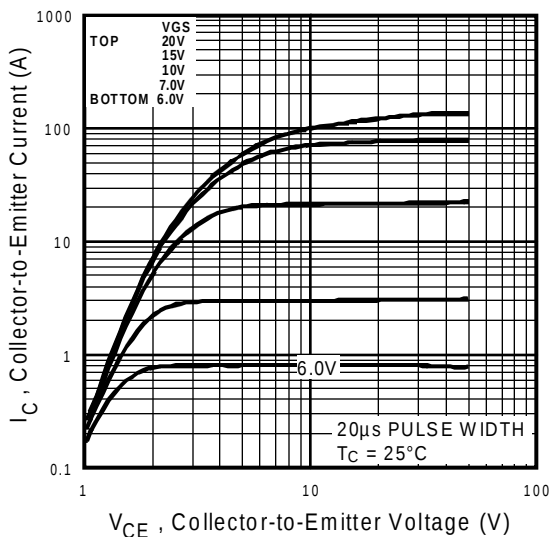


Fig. 2 - Typical Output Characteristics
 $T_C = 25^\circ\text{C}$

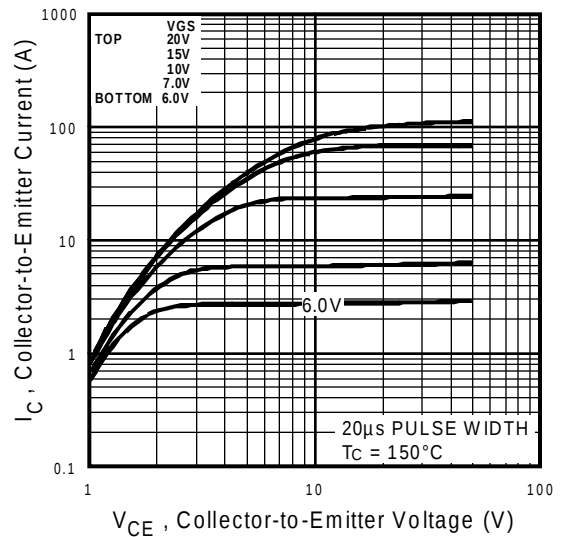


Fig. 3 - Typical Output Characteristics
 $T_C = 150^\circ\text{C}$

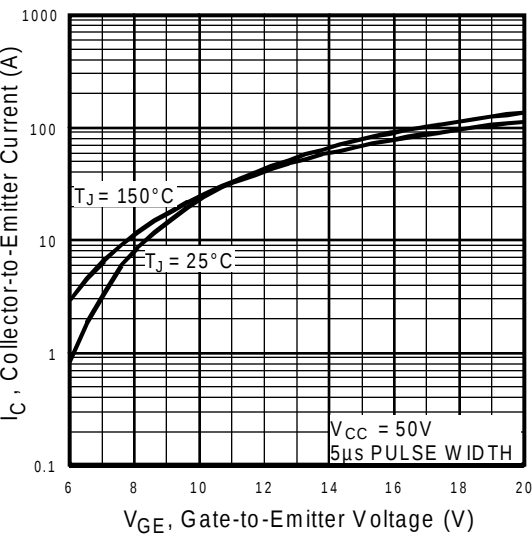


Fig. 4 - Typical Transfer Characteristics

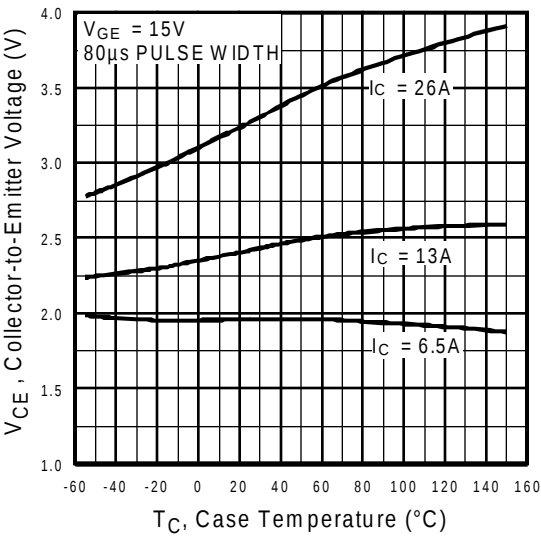


Fig. 5 - Collector-to-Emitter Voltage vs. Case Temperature

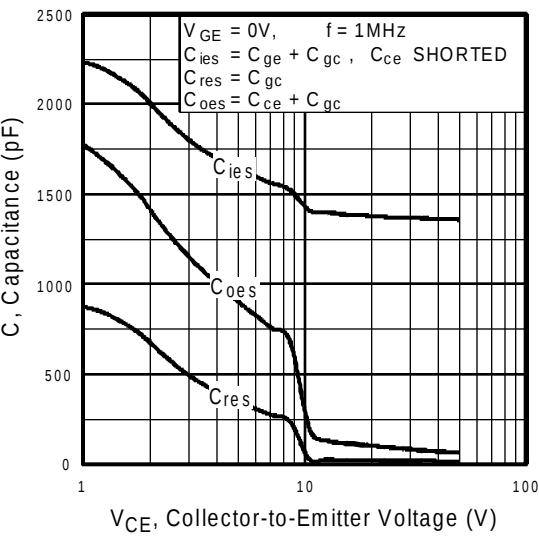


Fig. 6 - Typical Capacitance vs. Collector-to-Emitter Voltage

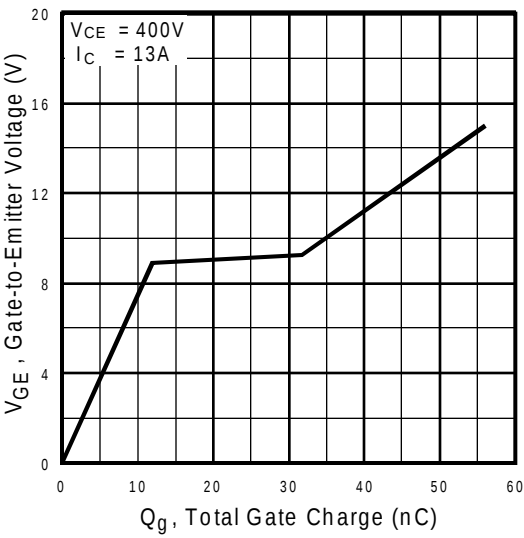


Fig. 7 - Typical Gate Charge vs. Gate-to-Emitter Voltage

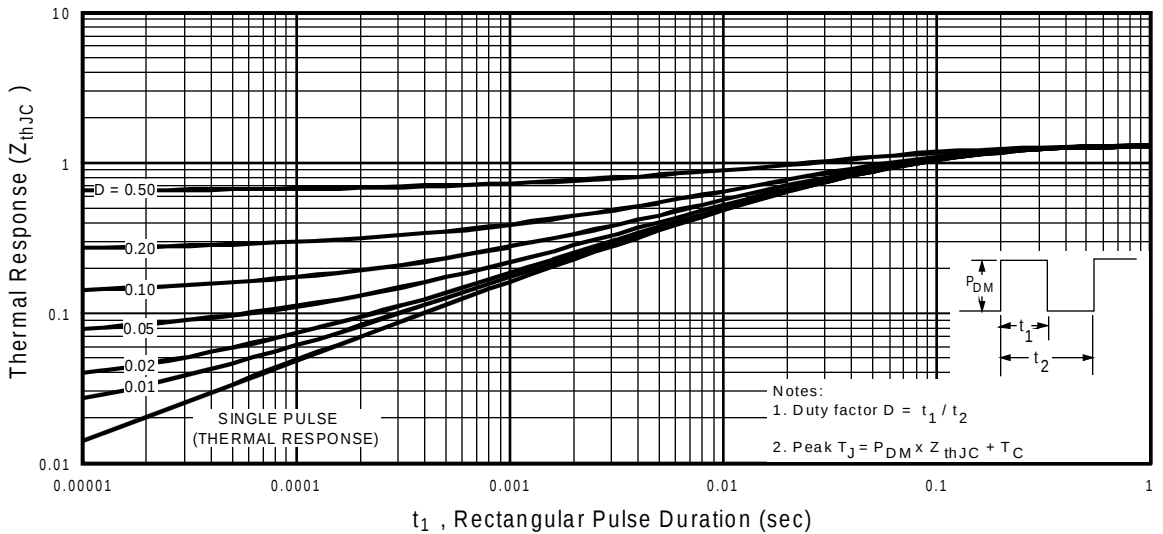


Fig. 8 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

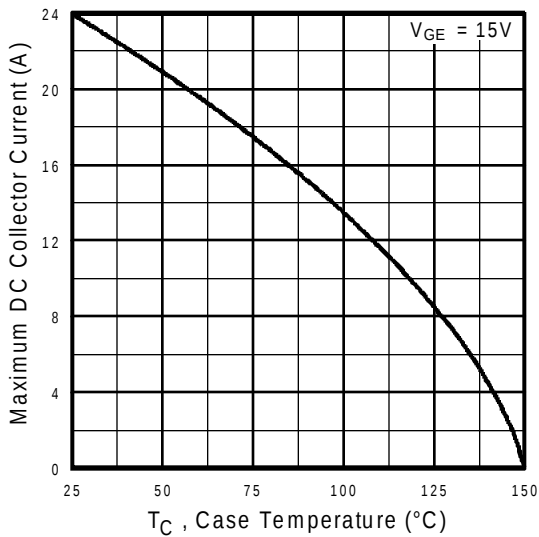


Fig. 9 - Maximum Collector Current vs. Case Temperature

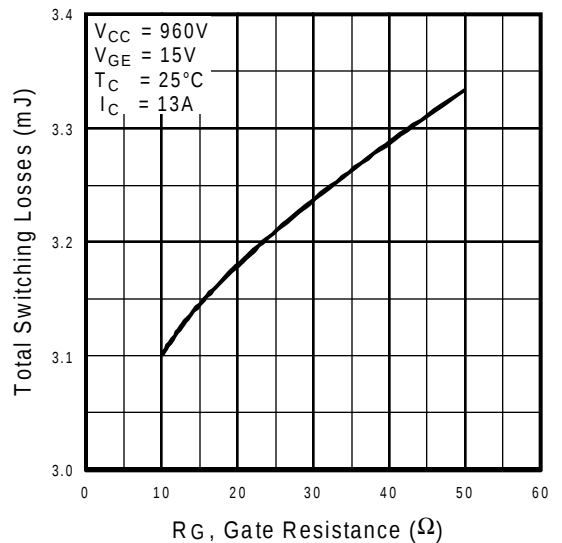


Fig. 10 - Typical Switching Losses vs. Gate Resistance

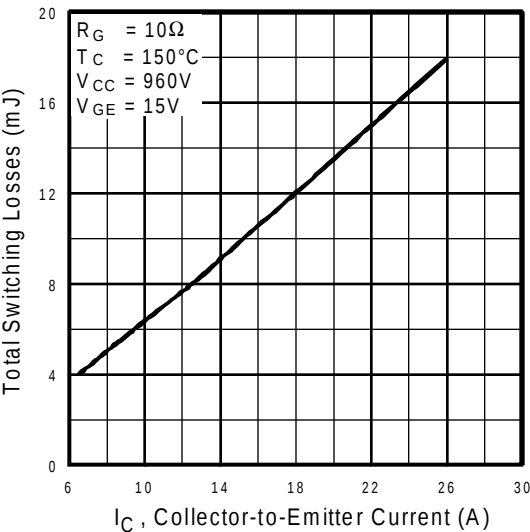


Fig. 11 - Typical Switching Losses vs. Collector-to-Emitter Current

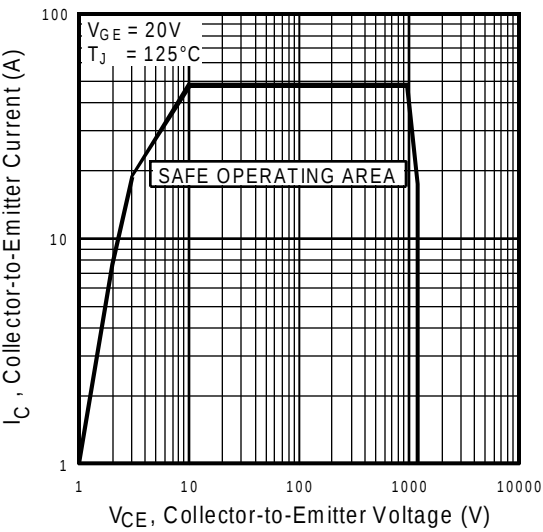


Fig. 12 - Turn-Off SOA

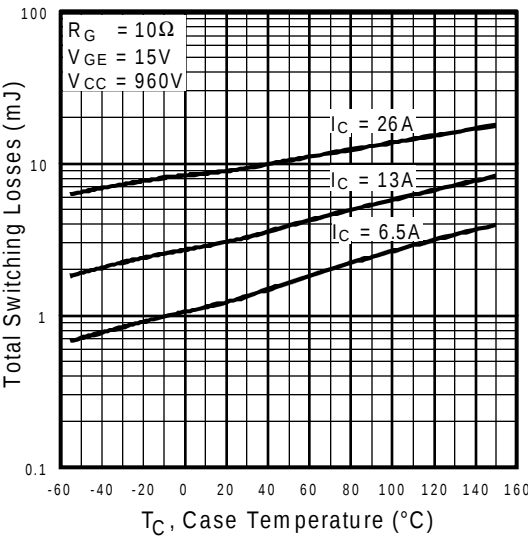
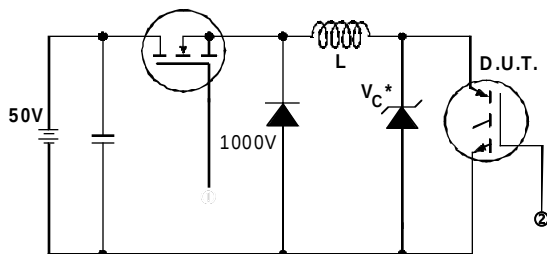


Fig. 13 - Typical Switching Losses vs. Case Temperature



* Driver same type as D.U.T.; $V_c = 80\%$ of $V_{ce(max)}$

* Note: Due to the 50V power supply, pulse width and inductor will increase to obtain rated I_d .

Fig. 13a - Clamped Inductive Load Test Circuit

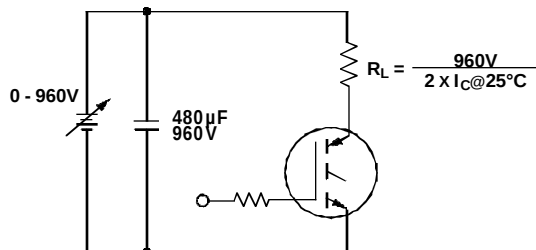


Fig. 13b - Pulsed Collector Current Test Circuit

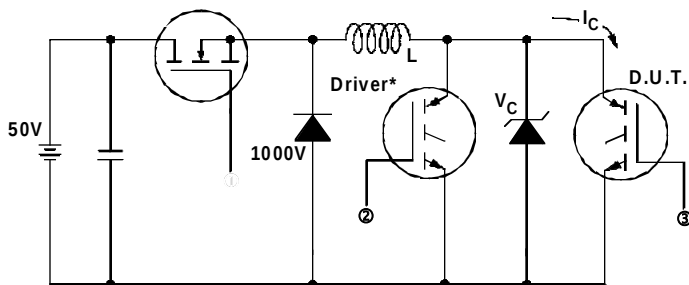


Fig. 14a - Switching Loss Test Circuit

* Driver same type as D.U.T., $V_C = 960V$

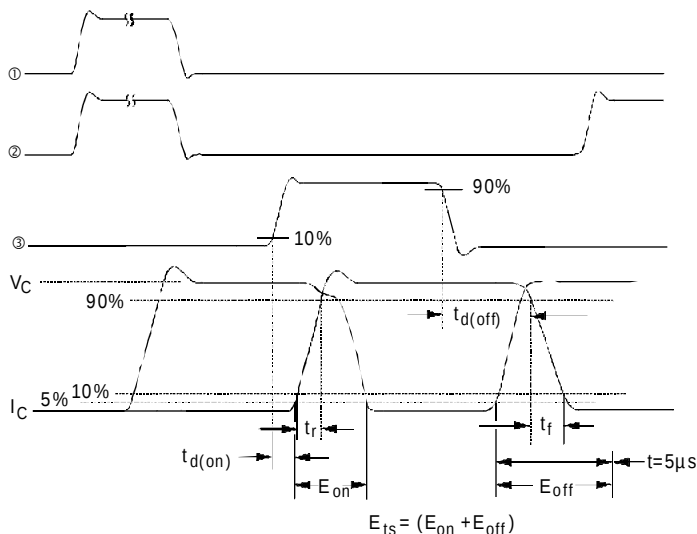


Fig. 14b - Switching Loss Waveforms

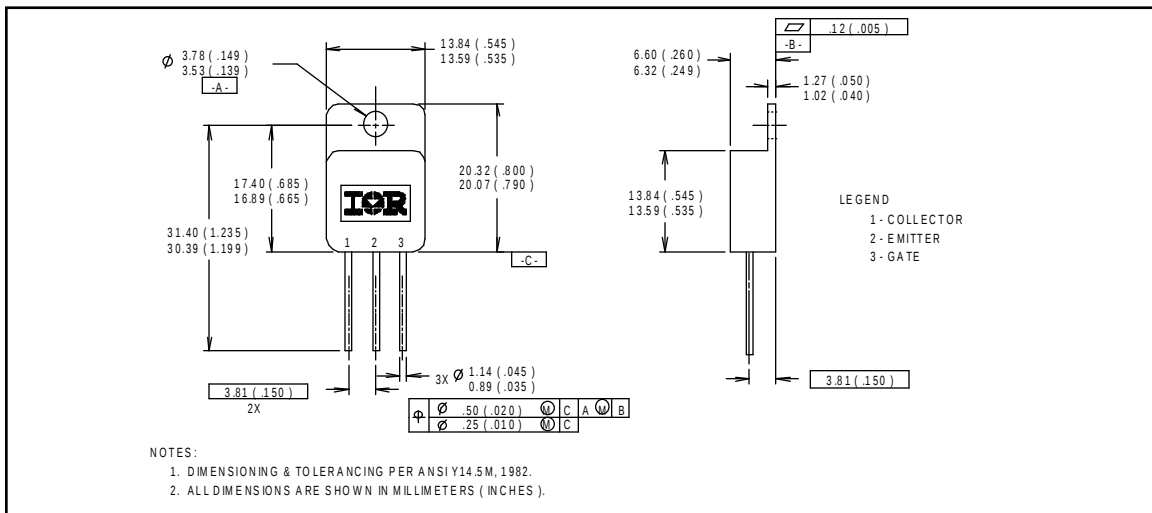


Fig. 15 - Conforms to JEDEC Outline TO-254AA
Dimensions in Millimeters and (Inches)

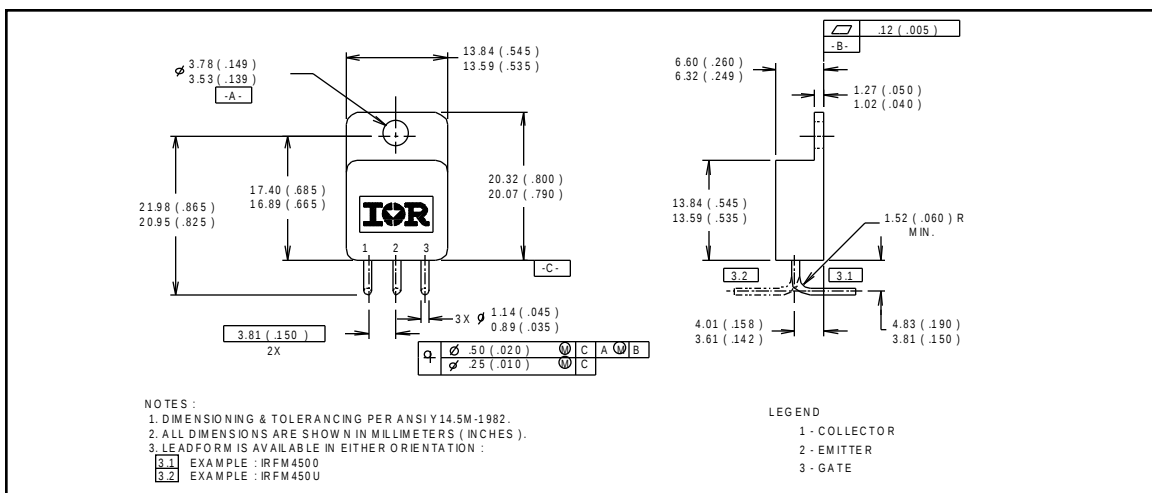


Fig. 16 - Optional Leadforms for TO-254

International IOR Rectifier

WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, Tel: (310) 322 3331

EUROPEAN HEADQUARTERS: Hurst Green, Oxted, Surrey RH8 9BB, UK Tel: ++ 44 1883 732020

IR CANADA: 7321 Victoria Park Ave., Suite 201, Markham, Ontario L3R 2Z8, Tel: (905) 475 1897

IR GERMANY: Saalburgstrasse 157, 61350 Bad Homburg Tel: ++ 49 6172 96590

IR ITALY: Via Liguria 49, 10071 Borgaro, Torino Tel: ++ 39 11 451 0111

IR FAR EAST: K&H Bldg., 2F, 3-30-4 Nishi-Ikeburo 3-Chome, Toshima-Ki, Tokyo Japan 171 Tel: 81 3 3983 0086

IR SOUTHEAST ASIA: 315 Outram Road, #10-02 Tan Boon Liat Building, Singapore 0316 Tel: 65 221 8371

<http://www.irf.com/>

Data and specifications subject to change without notice.

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